

US00D717255S

(12) **United States Design Patent**
Lim et al.

(10) **Patent No.:** **US D717,255 S**
(45) **Date of Patent:** **** Nov. 11, 2014**

- (54) **SEMICONDUCTOR DEVICE**
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(**) Term: **14 Years**

(21) Appl. No.: **29/450,510**

(22) Filed: **Mar. 18, 2013**

(30) **Foreign Application Priority Data**

Sep. 20, 2012 (KR) 30-2012-0045471

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/110, 182, 184; 361/713, 728, 736,
361/760, 761, 775, 679.01, 820; 257/666,
257/668, 678, 684, 690; 324/71.5, 252;
174/250, 253; 438/64, 65, 66
See application file for complete search history.

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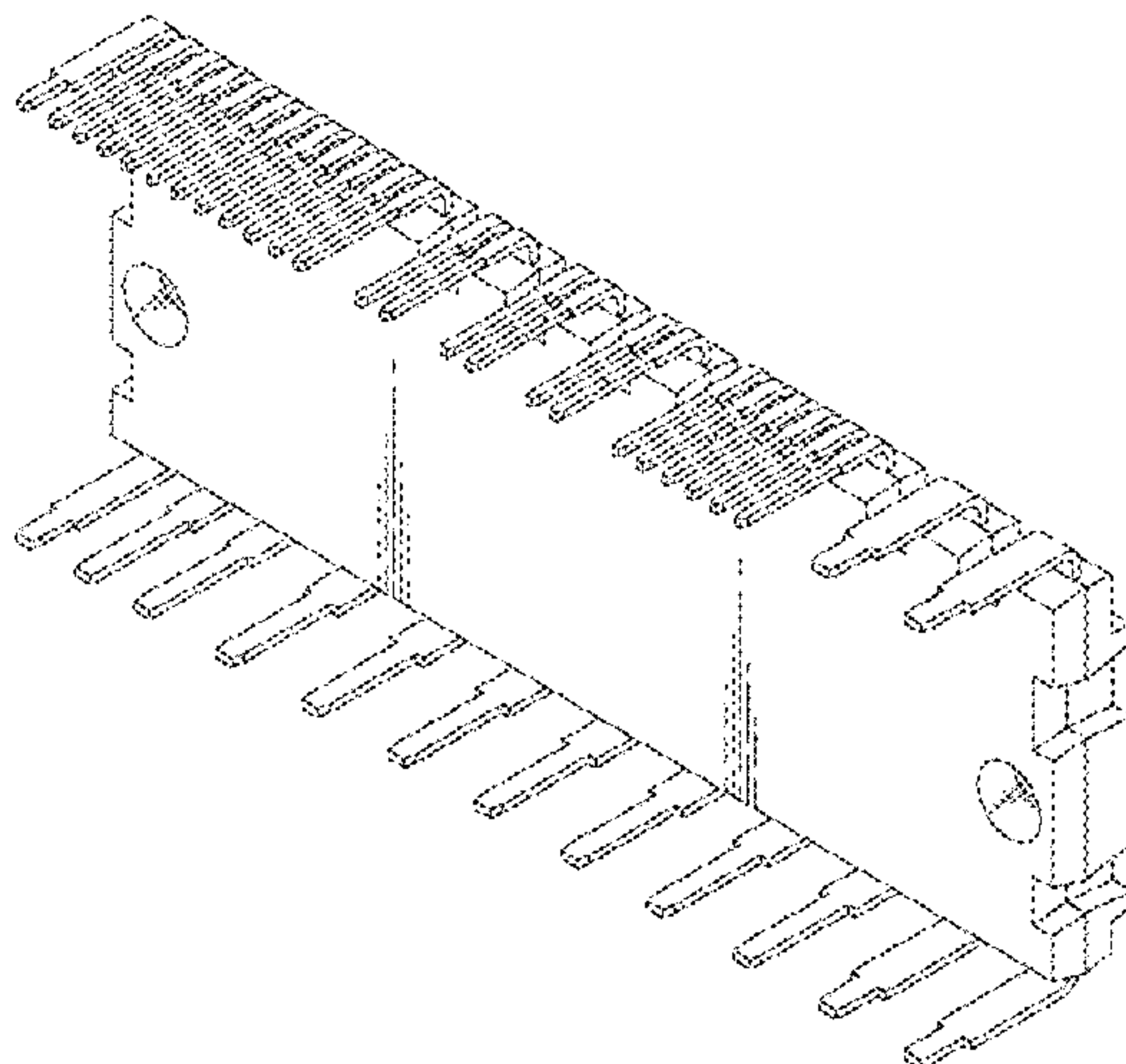
(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a semiconductor device showing our new design;
FIG. 2 is a front view thereof;
FIG. 3 is a rear view thereof;
FIG. 4 is a left side view thereof, the right side view thereof being a mirror image;
FIG. 5 is a top plan view thereof;
FIG. 6 is a bottom plan view thereof; and,
FIG. 7 is a cross sectional view thereof taken along lines 7-7 of FIG. 2.

1 Claim, 4 Drawing Sheets



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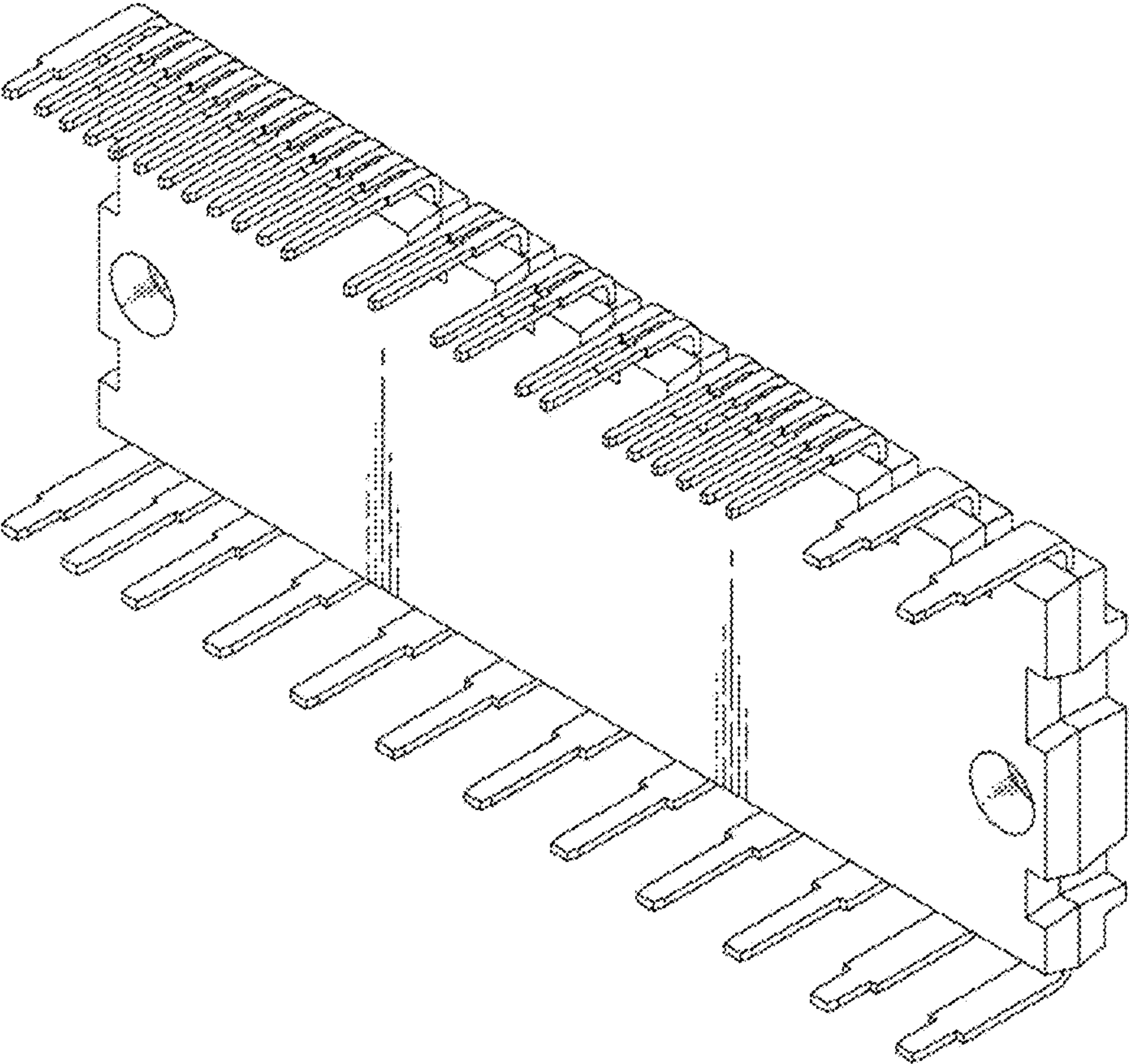


FIG. 1

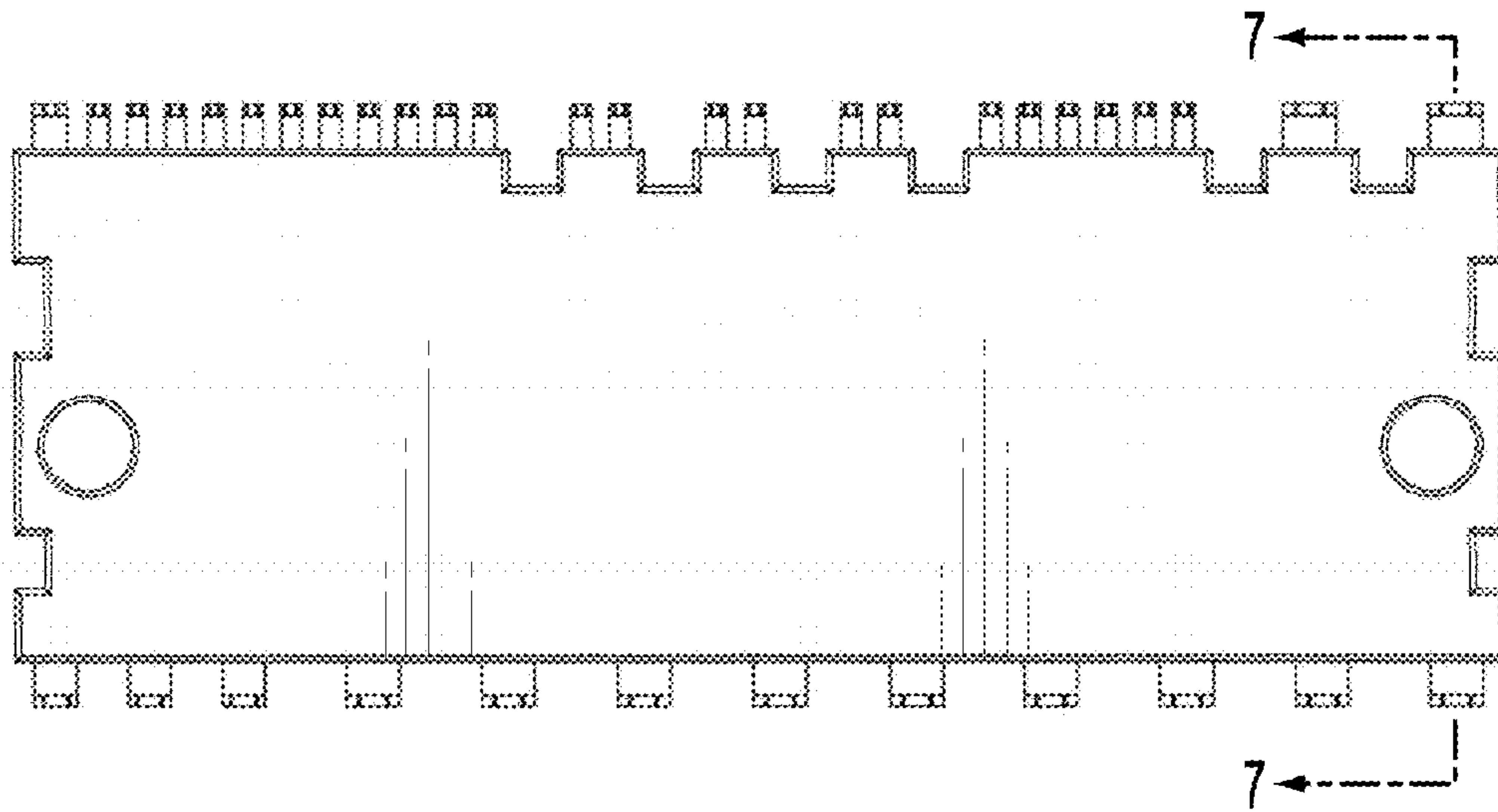


FIG. 2

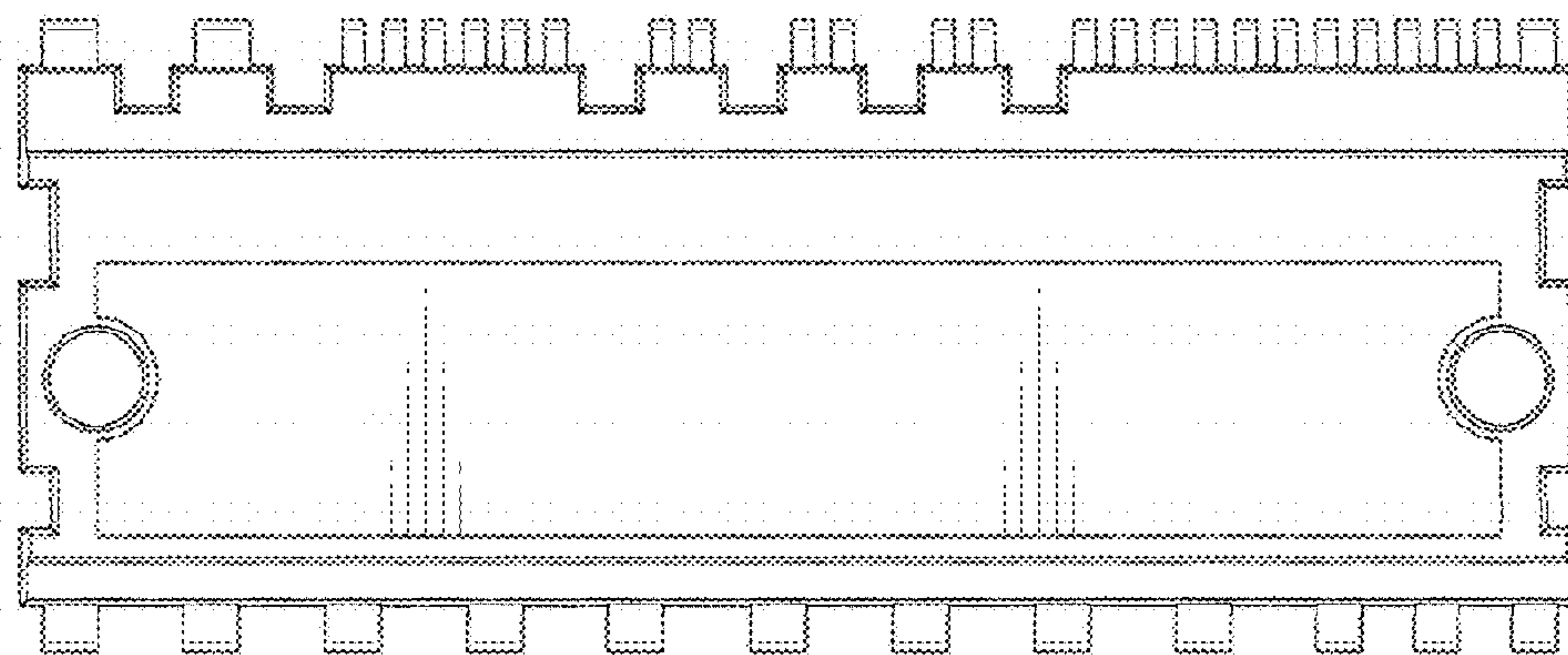


FIG. 3

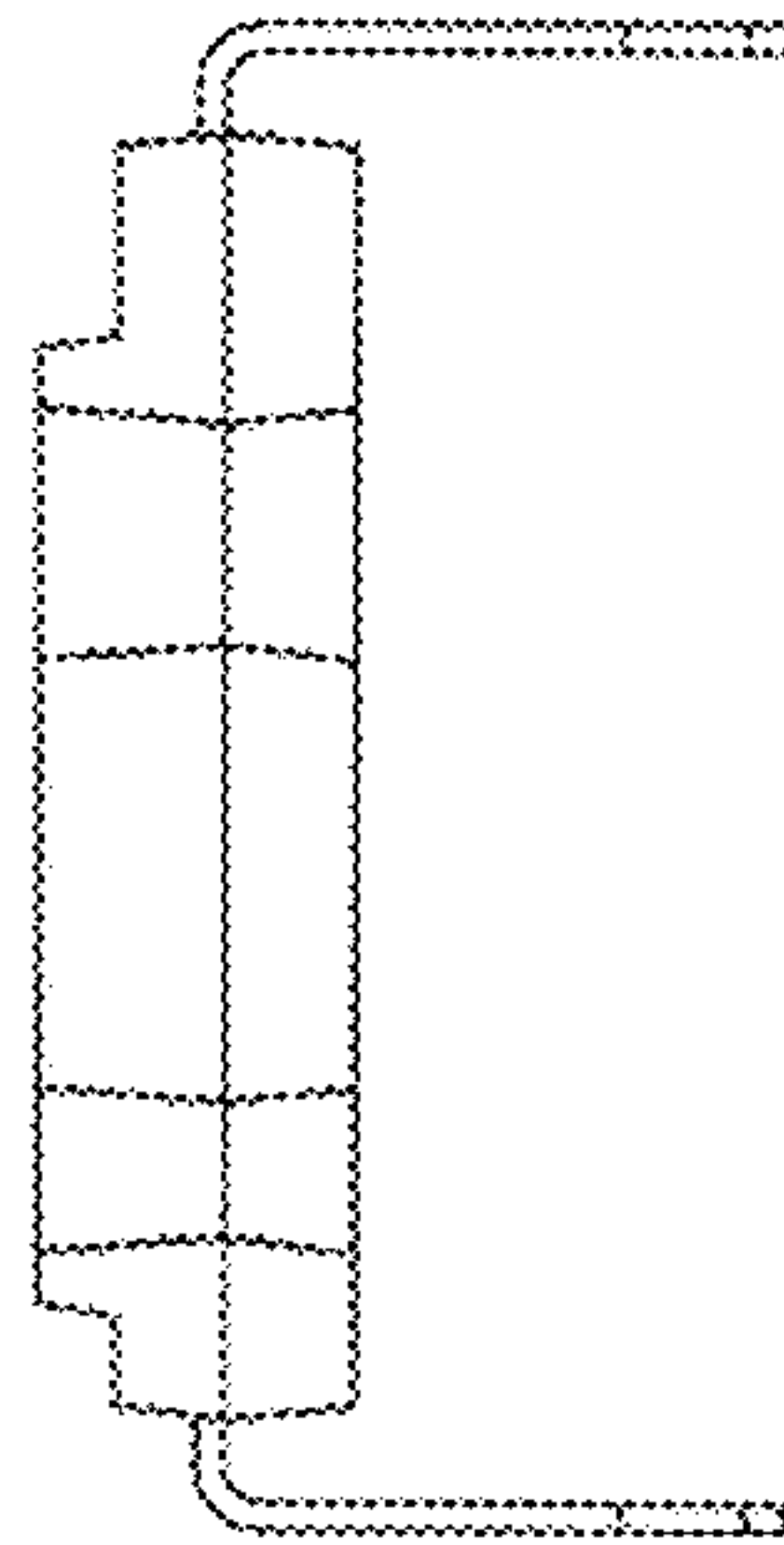


FIG. 4

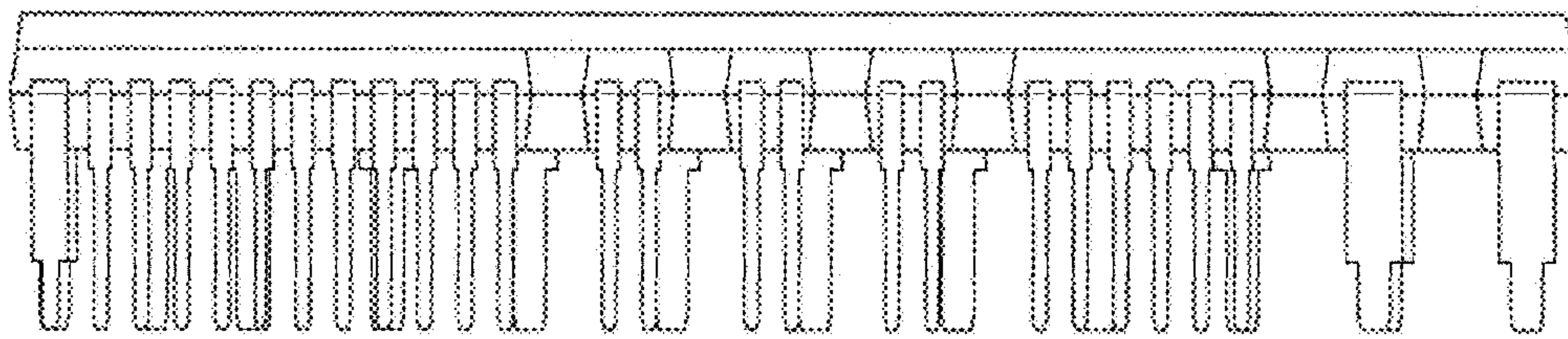


FIG. 5

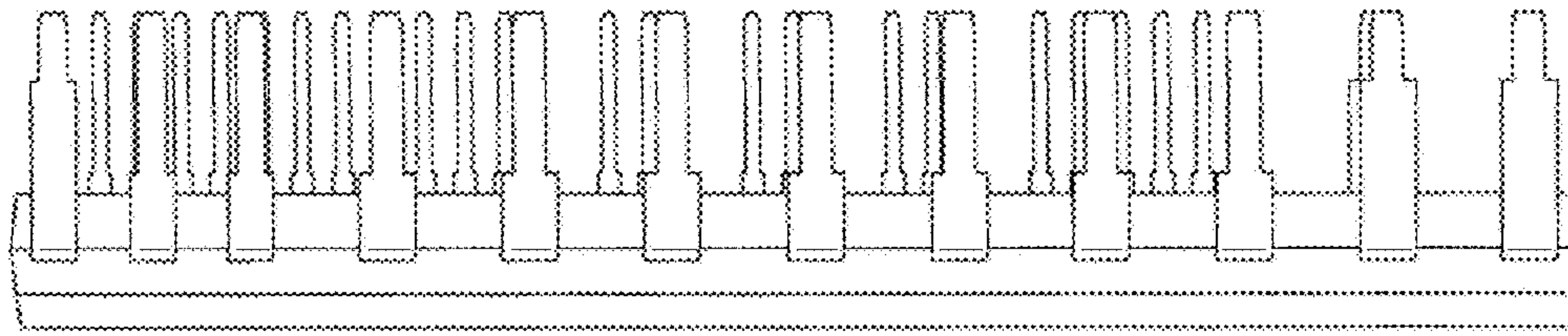


FIG. 6

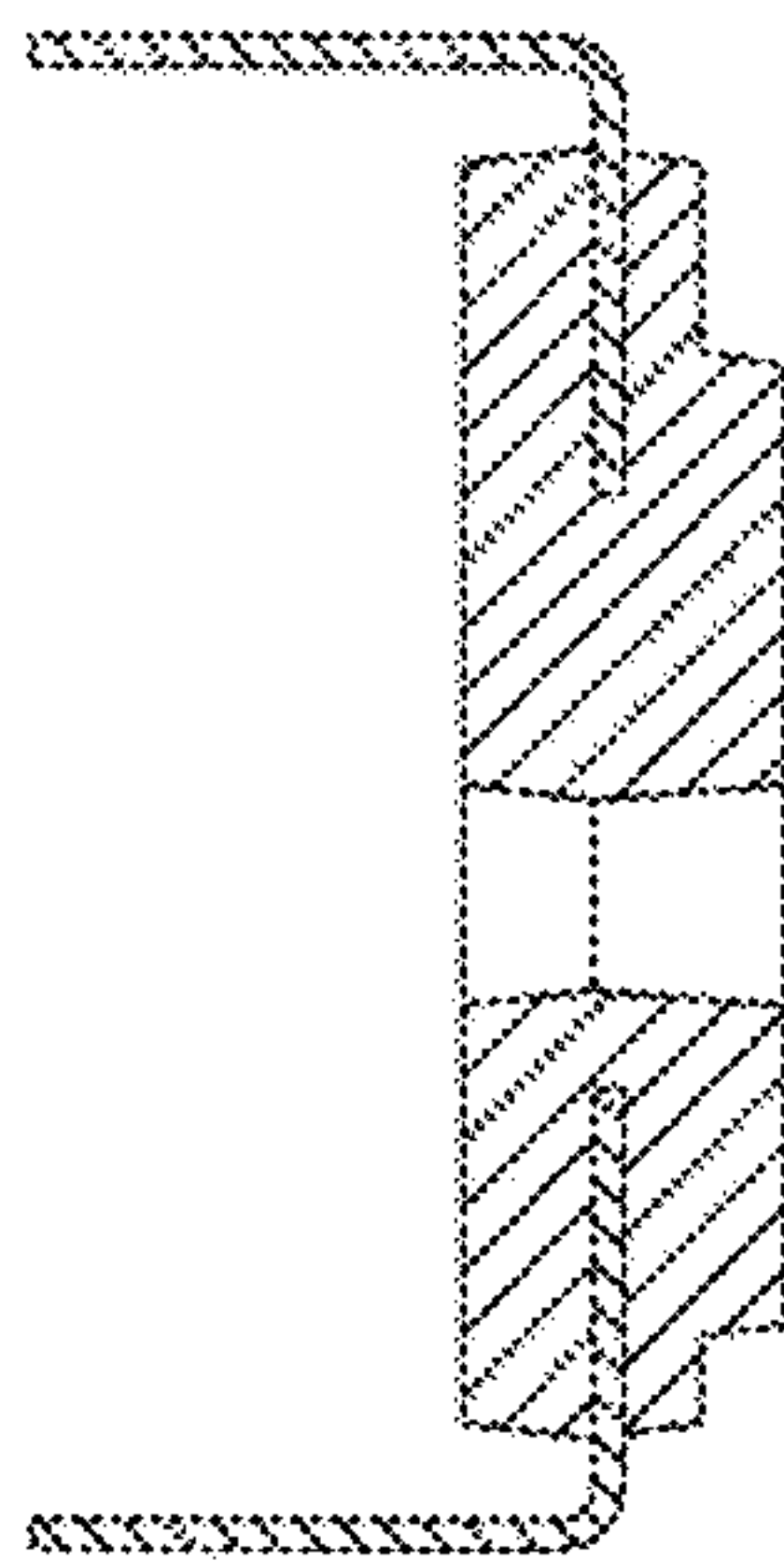


FIG. 7